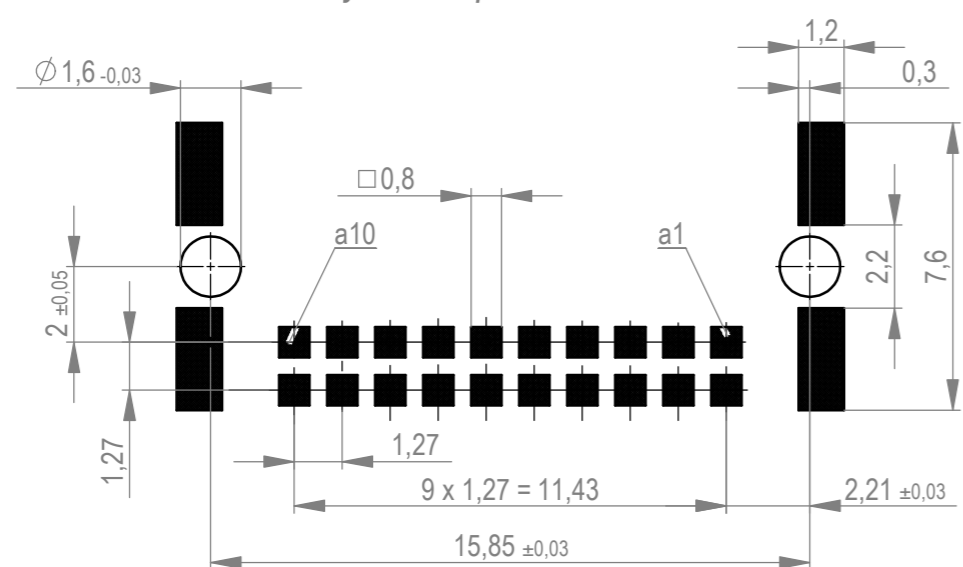
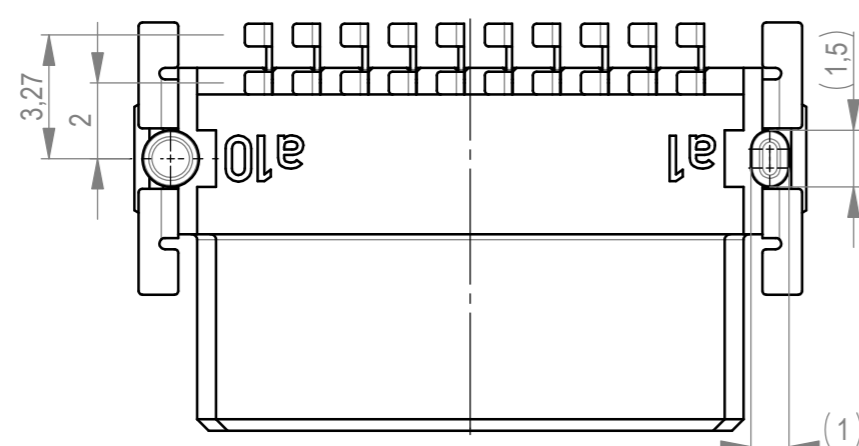
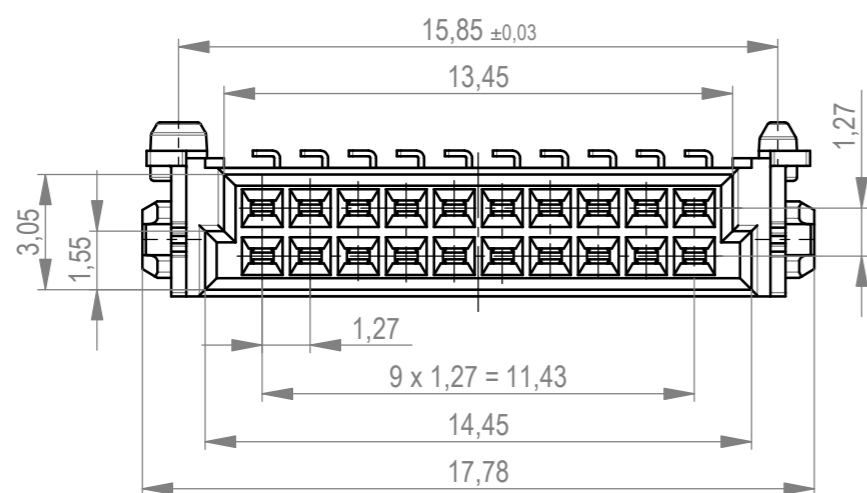
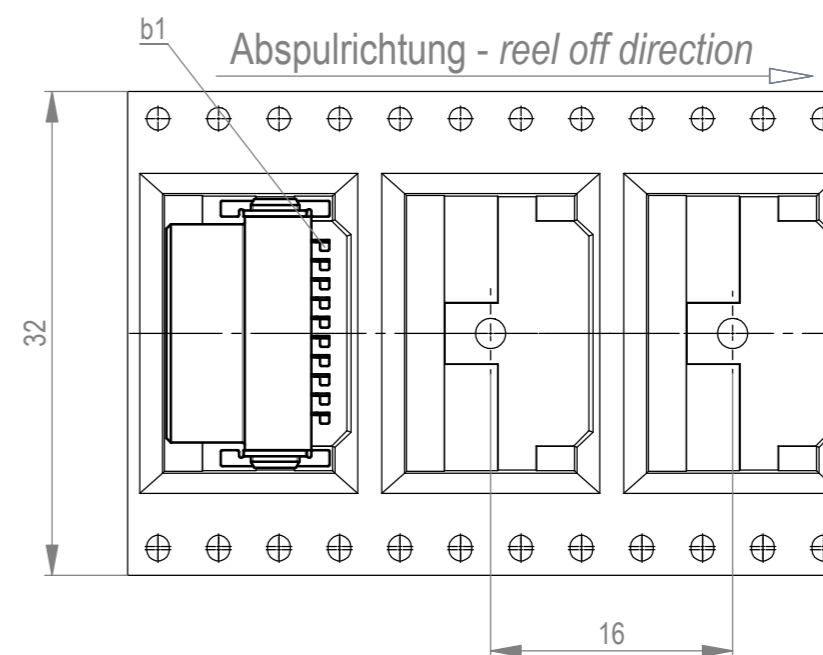
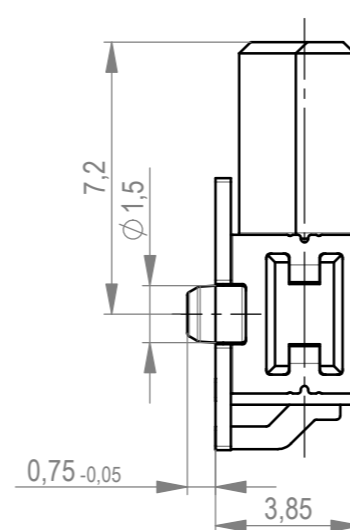
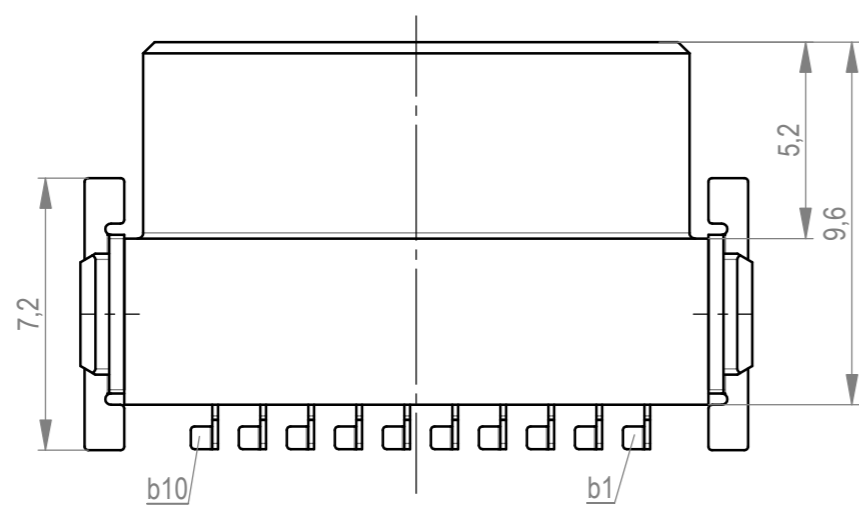
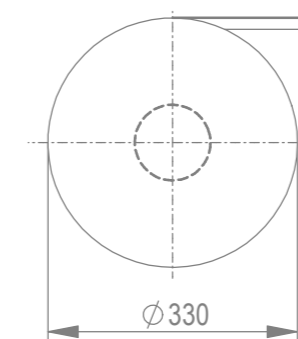


Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT



Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
tape on reel packaging according to DIN IEC 60286-3
Verpackungseinheit: 560 Stück
packaging unit: 560 pcs



Anforderungsstufe 1
performance level 1

Kontaktbereich vergoldet
mating area gold plating

Anschlussbereich verzinkt 4-6 µm
terminal area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
coplanarity area of termination ≤ 0,1 mm

BA7-03 - Standard Bauhöhe

type7-03 - standard assembly height

Wichtigste Version dieser Zeichnung dient zur Erreichung der
Handlung. Bei Abweichungen vom englischen Original gilt das
englische Original. In case of any deviation the English version shall prevail.

Dimension no.	Tolerances ISO 8015		Scale 5:1 Material
Customer drawing: All rights reserved. Only for information. To ensure that this is the latest version of this drawing, please contact one of the ERNI companies before using.	Subject to modification without prior notice. Drawing will not be updated.		Federl. SMC-Q 20-SMD-BA7-03 Female SMC-Q 20-SMD-type7-03
c Index	07.02.2020 Date		354079 I A2
		ERNI International AG Zürichstrasse 72 8306 Brüttisellen - Zürich Switzerland	Class SMCQ